

VERSION WITH MARKINGS TO SHOW CHANGES MADE

ABSTRACT OF THE DISCLOSURE

In a semiconductor device having CSP structure, reinforcing pads are provided on corners of the mounting surface of the CSP body portion, and a plurality of solder balls are mounted on the reinforcing pads, respectively. [In] Each of the reinforcing [pad 21 of a square or 22 of a triangle, at least portions on which a part of solder balls positioned outer side among a plurality of the solder balls are mounted are hemmed to have roundness in line with outer sides of predetermined portions of planes of the solder balls 12 connected with the CSP body portion 11] pads has a periphery adjacent to each of the solder balls mounted thereon that is at least semicircular, when seen in plan view. [Any] This structure avoids acute angle portions [are not produced in the hemmed portions. Mechanical] which mechanical stress is [therefore not] concentrated [on the hemmed portions]. As a result, [remove] peeling of solder balls [in] from the reinforcing pad can be reduced.

IN THE SPECIFICATION:

Page 8, the paragraph beginning on line 9 has been amended as follows:

--In the present invention, the semiconductor device according to the preferred embodiment is mounted on a principle surface (a surface on which the semiconductor device is mounted) of a substrate, such as a printed wiring substrate, and the like to be connected with a circuit formed on the principle surface. The semiconductor device comprises a body portion having a mounting surface (bottom surface), predetermined numbers of solder balls which are formed on the mounting surface (bottom surface) and which connect the semiconductor device to the principle surface of the printed wiring substrate, and the like. On corners of the bottom surface of the body portion, reinforcing pads are provided, respectively. A plurality of the solder balls are positioned (mounted) on each of the reinforcing pads. [In] Each of the reinforcing pads[, portions on which at least a part of solder balls positioned outer side among a plurality of the solder balls are mounted are hemmed in line with outer sides of predetermined portions of connected planes of the above-mentioned at least a part of solder balls positioned the outer side thereamong, respectively] has a periphery adjacent to each of the solder balls mounted thereon that is at least semicircular, when seen in plan view as in Figure 5A.--.